

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.62597	100.0	6.7
			Subtotal	0.62597	100	6.7
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00654	2.0	0.07
	Lead alloy	Silver (Ag)	7440-22-4	0.00817	2.5	0.0875
	Lead alloy	Lead (Pb)	7439-92-1	0.31228	95.5	3.3425
			Subtotal	0.32699	100	3.5
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01393	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.09287	100.0	0.99402
			Subtotal	0.1068	200	1.14312
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03746	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01124	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03746	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.37845	99.77	400.0777
			Subtotal	37.46461	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.83872	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.91399	10.0	63.3
	Filler	Silica fused	60676-86-0	50.26893	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11828	0.2	1.266
			Subtotal	59.13992	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.3357	100.0	25
			Subtotal	2.3357	100	25
			Total	99.99999	100	1070.34312

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